1. A method comprising:

attaching ligands along the length of a polymer to form a brush for cleaning semiconductor wafers.

2. The method of claim 1 including attaching ligands using a hydrolysis reaction.

3. The method of claim 1 including attaching ligands along the length of a polyvinyl alcohol polymer.

4. The method of claim 1 including using a coupling agent to attach ligands along the length of a polymer chain.

5. The method of claim 1 including attaching ligands to provide a hydrophilic property.

6. The method of claim 1 including attaching ligands to provide hydrophobic property.

7. The method of claim 1 including attaching ligands to provide a reducing agent property.

8. The method of claim 1 including attaching ligands to provide an oxidizing property.

9. The method of claim 1 including attaching ligands to provide an attraction to a specific material.

10. The method of claim 1 including attaching ligands to change the zeta potential.

11. The method of claim 1 including attaching a ligand having a subchain to the polymer.

12. The method of claim 11 including attaching a moiety to said subchain to provide a desired property to said ligand.

13. A method comprising:

cleaning a semiconductor wafer using a polymer brush having ligands attached along the length of a polymer.

14. The method of claim 13 including using a brush having ligands attached to polyvinyl alcohol polymer bristles.

15. The method of claim 13 including using a brush having ligands that to provide a hydrophilic property.

16. The method of claim 13 including using a brush having ligands that provide a hydrophobic property.

17. The method of claim 13 including using a brush having ligands that provide a reducing agent property.

18. The method of claim 13 including using a brush having ligands that provide an oxidizing property.

19. The method of claim 13 including using a brush having ligands that are attracted to a specific material.

20. The method of claim 13 including using a brush having ligands having a positive zeta potential.

21. The method of claim 13 including using a brush having ligands having a negative zeta potential.

22. The method of claim 13 including using a brush having a ligand having a subchain of at least two carbon atoms.

23. The method of claim 22 including using a brush having a moiety on said subchain to provide a desired property to said ligand.

24. A brush for cleaning semiconductor wafers comprising:

a polymer chain having ligands attached along the length of the chain.

25. The brush of claim 24 wherein said chain is a polyvinyl alcohol polymer chain.

26. The brush of claim 25 wherein said chain is a formal polyvinyl alcohol chain.

27. The brush of claim 24 wherein one of said ligands includes a hydrophilic moiety.

28. The brush of claim 24 wherein one of said ligands includes a hydrophobic moiety.

29. The brush of claim 24 wherein one of said ligands includes a reducing agent moiety.

30. The brush of claim 24 wherein one of said ligands includes an oxidizer.

31. The brush of claim 24 wherein one of said ligands includes a moiety attracted to a specific material.

32. The brush of claim 24 wherein one of said ligands includes a negative zeta potential moiety.

33. The brush of claim 24 wherein one of said ligands includes a positive zeta potential moiety.

34. The brush of claim 24 wherein one of said ligands is attached to a carbon chain having at least two carbon atoms.